Hybrid 7z63 Traveler

May 19, 2000

1 Connectivity

Repairs on shorts:
Fixes for opens:

2 Chips

The following chips were assembled on this hybrid (in the order that the chips get read out):
Hybrid 7Z63 has die: 158-077 158-080 158-081 158-083 158-084 158-085 158-087

3 Data Analysis Summary

The following summarizes the findings of the Burn-in data analysis program. The first chip in the readout name is numbered 0.

```
% Hybrid 7z63 classification info. Created 10:22:09 05/18/00

Hybrid 7z63 quality: fair
Chip classification: good good good good good good fair
Bad channels: none
Bad cells: none
Random bad capacitors (chip-cell-channel): 6-0-85 6-26-85 6-29-85
   6-30-85 6-32-85 6-34-85 6-36-85 6-45-84 6-45-85
Channels at pedestal needed for DCMS: 32.4 33.7 33.6 33.2 34.7 32.8 30.7
```

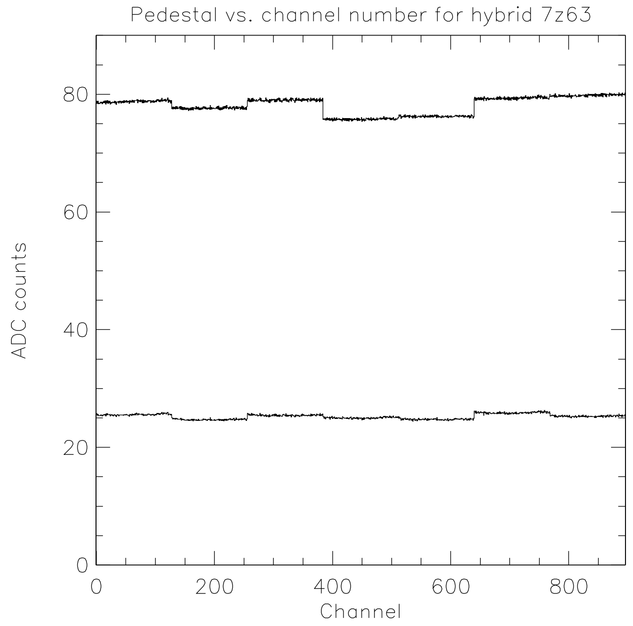
4 Comments

Encapsulated. FE DV finger gold bonds. HV tested.

5 Pedestal

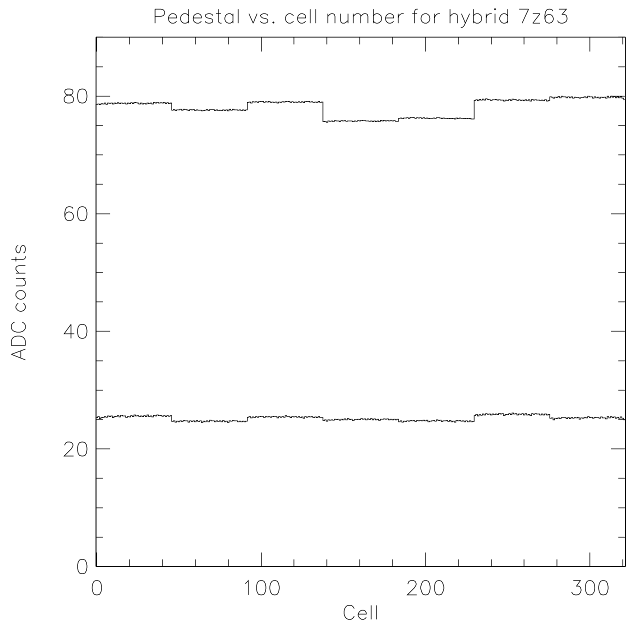
The following plot shows the pedestals vs. channel number with and without charge injection:

Pedestal for each Channel



The following plot shows the average pedestal vs. pipeline cell ID with and without charge injection. The x-axis is cell ID offset by 46 for each chip. Thus cell ID 5 for chip 1 is at x=5, chip 2 at x=51, chip 3 at x=97, etc.

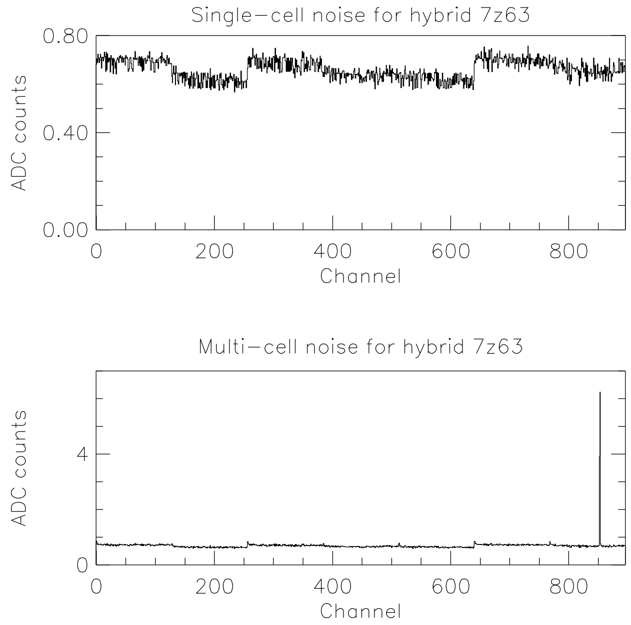
Pedestal vs. Pipeline Cell ID



6 Noise

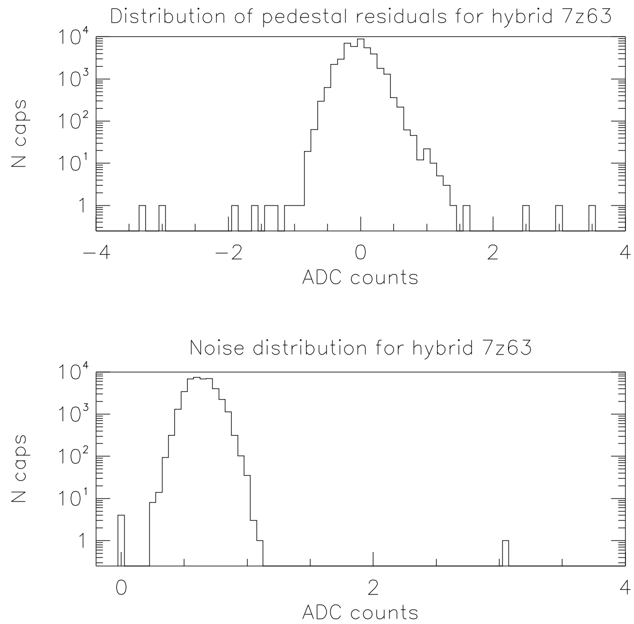
The following plots show the single-cell and multi-cell RMS noise:

RMS Noise



The following are histograms of the pedestal of each pipeline capacitor relative to the chip average (top); and the RMS noise of each capacitor (bottom):

Distribution of Pedestals and Noise



7 Currents

The following plots show the supply currents per chip as a function of measurment number. Currents are measured approximately every 10 minutes:

Supply Currents During Burn-in